

Title (en)

Plating bath and method for electroless deposition of nickel layers

Title (de)

Plattierbad und Verfahren zur stromlosen Abscheidung von Nickelschichten

Title (fr)

Bain de placage et procédé de dépôt anélectrolytique de couches de nickel

Publication

EP 3026143 A1 20160601 (EN)

Application

EP 14194890 A 20141126

Priority

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Abstract (en)

The present invention relates to aqueous plating bath compositions and methods for deposition of nickel and nickel alloys utilizing mixtures of stabilizing agents comprising metal ions of at least one of indium and gallium and iodine containing, inorganic compounds in order to enhance bath stability.

IPC 8 full level

C23C 18/32 (2006.01); **C23C 18/50** (2006.01)

CPC (source: CN EP KR US)

C23C 18/1646 (2013.01 - US); **C23C 18/36** (2013.01 - CN EP KR US); **C23C 18/50** (2013.01 - CN EP KR US)

Citation (applicant)

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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EP 3026143 A1 20160601; CA 2968437 A1 20160602; CA 2968437 C 20221122; CN 107109654 A 20170829; CN 107109654 B 20190827; EP 3224388 A1 20171004; EP 3224388 B1 20181017; ES 2705430 T3 20190325; JP 2017535674 A 20171130; JP 6667525 B2 20200318; KR 102497590 B1 20230207; KR 20170086051 A 20170725; MY 186470 A 20210722; TW 201623686 A 20160701; TW I683927 B 20200201; US 2017335462 A1 20171123; WO 2016083195 A1 20160602

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